



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION # 16767Generic Copy

Issue Date: 30-Nov-2011**TITLE:** SPEL as a second manufacturing Site for Product PCS3P8504AG-08CR**PROPOSED FIRST SHIP DATE:** 01-Mar-2012 or sooner upon customer's approval**AFFECTED CHANGE CATEGORY(S):** Assembly& Test Site**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or Raj Uppala<raj.uppala@onsemi.com>**SAMPLES:**Contact your local ON Semiconductor Sales Office or Raj Uppala<raj.uppala@onsemi.com>**ADDITIONAL RELIABILITY DATA:** AvailableContact your local ON Semiconductor Sales Office or Reliability Engineer Lakshmi Kari,
<Lakshmi.Kari@onsemi.com>**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.**DESCRIPTION AND PURPOSE:**

This Process Change Notice is to inform customers that ON Semiconductor is adding SPEL Semiconductor, India as a second manufacturing location for product PCS3P8504AG-08CR.

The devices listed on this FPCN have historically been assembled & tested at the HANA located in Thailand. Due to flooding in Thailand, the assembly/test site in Hana, Thailand is temporarily not in operation. Moving forward, these devices will be processed at either of the location based on the situation.

There will be no changes in device functionality. Reliability will continue to meet or exceed ON Semiconductor's highest standards.


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	Hana	SPEL
Frame	LF WDFN8 20X20 PPF	LF WDFN8 Cu-Ag Frames
Epoxy	DA 8006NS NON-CON	DA 8006NS NON-CON
Gold Wire	WIRE GOLD 1.0 MIL	WIRE GOLD 1.0 MIL
Mold	MC CEL9220HF13H HF	Sumitomo HCD770
Plating Finish	NiPdAu	100% Sn

There is a change in Lead finish assembled at SPEL.

There will be no changes in device functionality. Reliability will continue to meet or exceed ON Semiconductor's highest standards.

RELIABILITY DATA SUMMARY:
Reliability Test Results:

#	Test	Name	Test Conditions	End Point Req's	Test Results	(rej/ ss) PCS3PS550 AG-08-CR	(rej/ ss) PCS3PS550 AG-08-CR
					Read Point	Lot A	Lot B
1	Prep	Sample preparation and initial part testing	various	---	Initial Electrical	done	done
2	HTOL	High Temp Op Life	TA = 125°C for 1000 hours	c = 0, Room	1000 Hrs	0/77	0/77
3	PC	MSL1 Preconditioning	External Visual @ 40X Temperature Cycle @ Ta = -40 +60°C, 5 Cycles Stabilization Bake @ Ta = 125°C, 24 Hrs. Moisture soak @ Ta/RH = 85°C/85%, 168 Hrs. Solder Reflow @ 260°C, 3 Cycles.	c = 0, Room		340/340	340/340
4	TC-PC	Precond. Temp Cycle	-65/+150 C for 1000 cycles	c = 0, Room	1000 cyc	0/77	0/77
5	AC-PC	Precond. Autoclave	TA = 121 °C, RH=100%, P= 15 psig	c = 0, Room	168 hrs	0/78	0/78
6	HTSL	High Temperature Storage Life	TA=150C for 1000 Hrs	c = 0, Room	1000 Hrs	0/80	0/80
7	HAST	Highly Accelerate Stress Test	TA = 131°C, rh = 85%, p = 18.8 psig , bias	c = 0, Room	120 hrs	0/77	0/77
8	SD	Solderability	Steam aging at 93° C, 1 Hr Dipping at 245° C, 5 seconds		Results	Pass	Pass
9	ESD	Electro-static Discharge	Human Body Model(± 2 KV), Machine Model (± 200 V)	n/a	Results	Pass	Pass

Table 1: Reliability Evaluation Results for Device PCS3PS550AG-08-CR. Qualification Points in BOLD



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ELECTRICAL CHARACTERISTIC SUMMARY:

No changes in device functionality. Device parameters will continue to meet all data sheet specifications.

CHANGED PART IDENTIFICATION: NA

List of affected General Parts:

PCS3P8504AG-08CR